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PATENT

Docket No.: MSCP0009USA

102585319

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECORDING COVER SHEET



5 1. Assignor:

(1) Tsung-Hsi Yu

(2) Hung Chang

2. Assignee: MICRO-STAR INT'L CO., LTD

No.69,Li-Te Rd., Chung-Ho City,Taipei Hsien, Taiwan, R.O.C.

10 3. Nature of Conveyance: Assignment of patent

4. Reference number: Application filed herewith.

5. Correspondence to: Winston Hsu , Reg. No 41,526
Mord Michael Lewis, Reg. No 50,478
P.O. BOX 506
15 Merrifield, VA 22116
U.S.A.

6. Number of applications affected by this recording: 1

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7. Execution date of the document to be recorded: 05/19/2003

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Date: 6/11/2003

Winston Hsu

Winston Hsu
U.S. Patent Agent
Reg. No.: 41,526

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PATENT

REEL: 014193 FRAME: 0307

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

Name: Tsung-Hsi Yu Nationality: R.O.C.

Address: 5F, No. 113, Sec. 2, Ting-Chou Rd., Taipei City, Taiwan, R.O.C.

Name: Hung Chang Nationality: R.O.C.

Address: 5F, No. 91, Ching-Hua St., Taipei City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **MICRO-STAR INT'L CO., LTD.**
(hereinafter 'Assignee'), of (Assignee address)

No. 69, Li-Te Rd., Chung-Ho City, Taipei Hsien, Taiwan, R.O.C.

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"INTEGRATED HEAT-DISSIPATING MODULE"

Which is found in :

- (a) _____ U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 5/19/2003 (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Tsung-Hsi Yu

Tsung-Hsi Yu

Hung Chang

Hung Chang

Assignment, Page 2 of 2

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